

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An electronic device comprising:  
a substrate on which an interconnect pattern is formed;  
a chip component having a first surface on which an electrode is formed and a second surface opposite to the first surface, the chip component being mounted in such a manner that the second surface faces the substrate, the chip component having a passivation film formed on the first surface;  
an insulating section formed of a resin and provided adjacent to the chip component; and  
an interconnect which is formed to extend from above the electrode, over the insulating section, on the passivation film, and ~~to~~ above the interconnect pattern, the insulating section being formed so that part of the insulating section under the interconnect does not overlay the first surface.
2. (Withdrawn) The electronic device as defined by claim 1,  
wherein a side surface of the chip component is inclined to descend in an outward direction from the first surface.
3. (Withdrawn) The electronic device as defined by claim 1,  
wherein the chip component has a step in an edge portion of the chip component.
4. (Withdrawn) The electronic device as defined by claim 1,  
wherein the insulating section is formed so that part of the insulating section overlays the first surface.
5. (Canceled)

6. (Withdrawn) The electronic device as defined by claim 1,  
wherein the insulating section has a portion higher than the first surface.
7. (Original) The electronic device as defined by claim 1, further comprising:  
a connection layer that connects the chip component with the substrate.
8. (Original) The electronic device as defined by claim 7,  
wherein the connection layer is formed of the same material as the insulating  
section.
9. (Original) The electronic device as defined by claim 7,  
wherein the connection layer is formed of a material different from a material  
of the insulating section.
10. (Currently Amended) An electronic device comprising:  
a substrate on which an interconnect pattern is formed;  
a chip component having a first surface on which an electrode is formed and a  
second surface opposite to the first surface, the chip component being mounted in such a  
manner that the second surface faces the substrate, the chip component having a passivation  
film formed on the first surface;  
an insulating section provided adjacent to the chip component and having an  
inclined surface descending in an outward direction from the chip component; and  
an interconnect which is formed to extend from above the electrode, over the  
insulating section, on the passivation film, and ~~to~~ above the interconnect pattern, the  
insulating section being formed so that part of the insulating section under the interconnect  
does not overlay the first surface.
11. (Withdrawn) The electronic device as defined by claim 10,  
wherein the inclined surface is a depressed surface.
12. (Withdrawn) The electronic device as defined by claim 10,

wherein the inclined surface is a projected surface.

13. (Withdrawn) The electronic device as defined by claim 10,  
wherein the insulating section is formed so that part of the insulating section  
overlays the first surface.

14. (Canceled)

15. (Withdrawn) The electronic device as defined by claim 10,  
wherein the insulating section has a portion higher than the first surface.

16. (Original) The electronic device as defined by claim 10, further comprising:  
a connection layer that connects the chip component with the substrate.

17. (Original) The electronic device as defined by claim 16,  
wherein the connection layer is formed of the same material as the insulating  
section.

18. (Original) The electronic device as defined by claim 16,  
wherein the connection layer is formed of a material different from a material  
of the insulating section.

19-30. (Canceled)

31. (Withdrawn) A circuit board on which an electronic device as defined in  
claim 1 is mounted.

32. (Withdrawn) A circuit board on which an electronic device as defined in  
claim 10 is mounted.

33. (Withdrawn) An electronic instrument having an electronic device as defined  
in claim 1.

34. (Withdrawn) An electronic instrument having an electronic device as defined  
in claim 10.